



ACTIVE project

Update on WP1

(3D + planar sensors)

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Milestones and Deliverables WP1

Date	Milestone
30/06/2014	Preliminary process tests completed and technology chosen
31/08/2014	First 3D sensor layout submitted
31/12/2014	Planar sensor layout submitted
31/03/2015	Wafer tests on first 3D sensor batch completed
30/06/2015	Wafer tests on planar sensor batch completed
31/08/2015	Second 3D sensor layout submitted
31/03/2016	Wafer tests on second 3D sensor batch completed

Year	Deliverable
2014	First 3D sensor batch
2015	Planar sensor batch
2015	Second 3D sensor batch



Fabrication cost estimate

Years	Cost (Euro)	Description
2014	25000	6" Wafer procurement (SOI, wafer bonding, epitaxial)
2014	15400	Initial technological tests at FBK (etching, thinning, ...)
2014	30000	First 3D sensor batch at FBK («convenzione»)
2015	15400	Planar sensor batch at FBK («convenzione»)
2015	60000	Second 3D sensor batch at FBK (NO «convenzione»)
2015-2016	50000 (*)	Post-processing (support wafer / epi removal, back-side metallization, ...)
2014-2016	195800	TOTAL

(*) If all processing at FBK, savings possible.